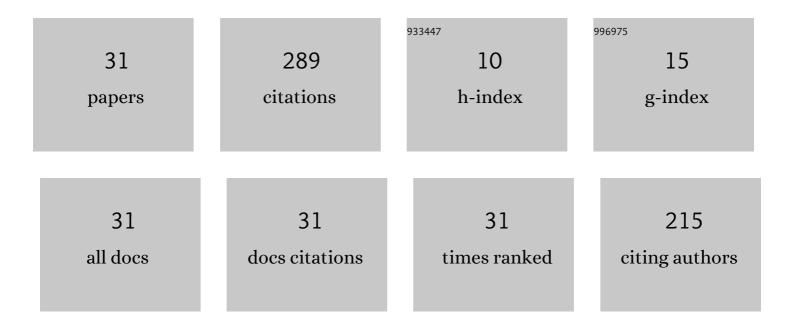
## Peter Filipp Fuchs

List of Publications by Year in descending order

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#	Article	IF	CITATIONS
1	Mechanical behavior of <scp>3D</scp> â€printed polymeric metamaterials for lightweight applications. Journal of Applied Polymer Science, 2022, 139, 51618.	2.6	15
2	Matrix–fiber interfacial debonding in soft composite materials: Cyclically behavior modeling and microstructural evolution. Composites Part B: Engineering, 2022, 237, 109853.	12.0	3
3	Towards electro-thermo-mechanical lifetime assessment for arbitrary power electronics. Microelectronics Reliability, 2022, 133, 114537.	1.7	2
4	A Review on Modeling Cure Kinetics and Mechanisms of Photopolymerization. Polymers, 2022, 14, 2074.	4.5	33
5	Asymmetric chiral and antichiral mechanical metamaterials with tunable Poisson's ratio. APL Materials, 2022, 10, .	5.1	9
6	Investigation of adhesion properties in load coupling applications for flexible composites. Materials Today: Proceedings, 2021, 34, 41-46.	1.8	7
7	The contribution of mechanical interactions to the constitutive modeling of fiber-reinforced elastomers. European Journal of Mechanics, A/Solids, 2021, 85, 104081.	3.7	15
8	Elastic load coupling with tailored elastomer composites. Composites Part C: Open Access, 2021, 4, 100088.	3.2	0
9	Quantifying matrix-fiber mechanical interactions in hyperelastic materials. International Journal of Mechanical Sciences, 2021, 195, 106268.	6.7	2
10	Functional mechanical metamaterial with independently tunable stiffness in the three spatial directions. Materials Today Advances, 2021, 11, 100155.	5.2	12
11	Analysis of the critical stresses in high-voltage composite winding insulations under thermal loads. Journal of Composite Materials, 2020, 54, 2073-2084.	2.4	Ο
12	Influence of Fiber Orientation and Adhesion Properties On Tailored Fiber-reinforced Elastomers. Applied Composite Materials, 2020, 27, 149-164.	2.5	12
13	Comparison and Impact of Different Fiber Debond Techniques on Fiber Reinforced Flexible Composites. Polymers, 2020, 12, 472.	4.5	13
14	Fracture mechanical characterization of mica-filled epoxy glass composites under monotonic and cyclic loading. Journal of Composite Materials, 2019, 53, 741-751.	2.4	3
15	Comparison of steady-state and transient thermal conductivity testing methods using different industrial rubber compounds. Polymer Testing, 2019, 80, 106121.	4.8	34
16	A Sequential Finite Volume Method / Finite Element Analysis of a Power Electronic Semiconductor Chip. , 2019, , .		1
17	Numerical Analysis of the Influence of Polymeric Materials on a MEMS Package Performance Under Humidity and Temperature Loads. , 2019, , .		3
18	Model free kinetics coupled with finite element method for curing simulation of thermosetting epoxy resins. Journal of Applied Polymer Science, 2018, 135, 46408.	2.6	10

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19	Heat Dissipation in Epoxy/Amine-Based Gradient Composites with Alumina Particles: A Critical Evaluation of Thermal Conductivity Measurements. Polymers, 2018, 10, 1131.	4.5	15
20	Evaluation of Digital Image Correlation Techniques for the Determination of Coefficients of Thermal Expansion for Thin Reinforced Polymers , 2018, , .		2
21	Influence of environmental factors like temperature and humidity on MEMS packaging materials. , 2018, , .		3
22	Modeling of manufacturing induced residual stresses of viscoelastic epoxy mold compound encapsulations. , 2017, , .		5
23	Finite element analysis of arbitrarily complex electronic devices. , 2016, , .		7
24	Numerical simulation of the electrical performance of printed circuit boards under cyclic thermal loads. Microelectronics Reliability, 2016, 62, 148-155.	1.7	5
25	Cyclic mechanical behavior of thin layers of copper: A theoretical and numerical study. Journal of Strain Analysis for Engineering Design, 2016, 51, 161-169.	1.8	5
26	Method development for the cyclic characterization of thin copper layers for PCB applications. Circuit World, 2014, 40, 53-60.	0.9	8
27	Local damage simulations of printed circuit boards based on inâ€plane cohesive zone parameters. Circuit World, 2013, 39, 60-66.	0.9	6
28	PCB drop test lifetime assessment based on simulations and cyclic bend tests. Microelectronics Reliability, 2013, 53, 774-781.	1.7	11
29	Determination of the orthotropic material properties of individual layers of printed circuit boards. Microelectronics Reliability, 2012, 52, 2723-2730.	1.7	26
30	Experimental Determination of Cohesive Zone Models for Epoxy Composites. Experimental Mechanics, 2011, 51, 779-786.	2.0	19
31	Cyclic bend tests for the reliability evaluation of printed circuit boards under dynamic loads. Frattura Ed Integrita Strutturale, 2011, 5, 64-73.	0.9	3